



Material Content Data Sheet



Sales Product Name		IPD06P005L		Issued		9. January 2019		
MA#		MA001782076						
Package		PG-TO252-3-313		Weight*		316.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.798	0.25	0.25	2519	2519
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		465	
	non noble metal	copper	7440-50-8	147.096	46.42	46.48	464223	464827
	non noble metal	aluminium	7429-90-5	0.560	0.18	0.18	1766	1766
wire	non noble metal	aluminium	7429-90-5	0.560	0.18	0.18	1766	1766
encapsulation	organic material	carbon black	1333-86-4	1.428	0.45		4507	
	plastics	epoxy resin	-	24.992	7.89		78872	
	inorganic material	silicondioxide	60676-86-0	116.390	36.73	45.07	367318	450697
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11803	11803
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4483	4494
solder	non noble metal	tin	7440-31-5	0.021	0.01		66	
	noble metal	silver	7440-22-4	0.026	0.01		82	
	non noble metal	lead	7439-92-1	0.997	0.31	0.33	3145	3293
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.05	6.06	60522	60601
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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